NL3S22S

USB 2.0 + Audio Switch

The NL3S22S is a double−pole/double−throw (DPDT) analog switch for routing high speed differential data and audio. The high−speed data path is compliant with High Speed USB 2.0, Full Speed USB 1.1, Low Speed USB 1.0 and any generic UART protocol. The multi−purpose audio path is capable of passing signals with negative voltages as low as 2 V below ground and features shunt resistors to reduce Pop and Click noise in the audio system.

Features

- V_{CC} Range: 2.7 V to 5.5 V
- Control Pins Compatible with 1.8 V Interfaces
- I_{CC}: 23 μA (Typ)
- ESD Performance: 4 kV HBM
- Available in 1.4 mm x 1.8 mm UQFN10
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

High Speed Data Path

- Input Signal Range: 0 V to 3.7 V
- $R_{DS(on)}$: 5 Ω (Typ)
- C_{ON}: 4.5 pF (Typ)
- Data Rate: USB 2.0–Compliant – up to 480 Mbps

Audio Path

- Input Signal Range: −2.0 V to 2.0 V
- R_{DSON}: 3 Ω (Typ)
- $R_{ON(FLAT)}$: 0.002 Ω (Typ)
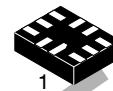- THD: 0.002% (R_L = 16 Ω / V_{IS} = 0.4 V_{RMS})

Applications

- Smartphones
- Tablets
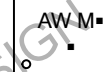- USB 2.0 Hosts/Peripherals
- Audio / High−Speeds Data Switching

ON Semiconductor®

MARKING DIAGRAM

UQFN10
CASE 488AT

AW M▪
○
▪

AW = Device Code
M = Date Code
▪ = Pb−Free Device

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NL3S22SMUTAG	UQFN10 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

DISCONTINUED
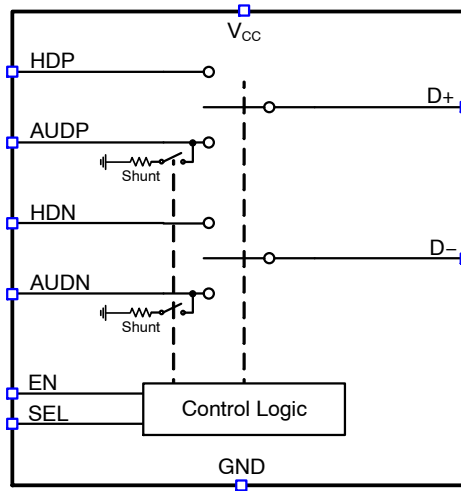THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGN
PLEASE CONTACT YOUR onsemi REPRESENTATIVE FOR INFORMATION

NL3S22S

Figure 1. Block Diagram

FUNCTION TABLE

EN	SEL	Shunt Status	D+/D− Function
0	X	ON	No Connect
1	0	OFF	AUDP/AUDN
1	1	ON	HDP/HDN
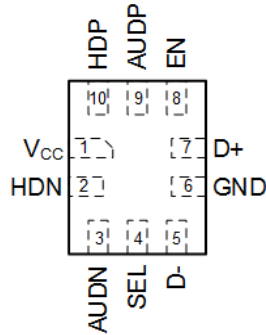
Figure 2. UQFN10 – Top Through View

PIN DESCRIPTION

Pin Name	Pin	Description
V$_{CC}$	1	Power Supply
HDN	2	High Speed Differential Data (−)
AUDN	3	Audio Signal (−)
SEL	4	Function Select
D−	5	Audio/Data Common I/O (−)
GND	6	Ground
D+	7	Audio/Data Common I/O (+)
EN	8	Chip Enable
AUDP	9	Audio Signal (+)
HDP	10	High Speed Differential Data (+)

NL3S22S

MAXIMUM RATINGS

Rating	Symbol		Value	Unit
V$_{CC}$	Positive DC Supply Voltage		−0.3 to +6	V
V$_{IS}$	Analog Input/Output Voltage	HDP, HDN	−0.3 to +5.5	V
		AUDP, AUDN	−2.5 to V$_{CC}$ + 0.3	
		D+, D−	−2.5 to +5.5	
V$_{IN}$	Digital Control Pin Voltage on EN, SEL		−0.3 to V$_{CC}$ + 0.3	V
T$_s$	Storage Temperature		−55 to +150	°C
T$_L$	Lead Temperature, 1 mm from Case for 10 seconds		260	°C
T$_J$	Junction Temperature Under Bias		150	°C
MSL	Moisture Sensitivity (Note 1)		Level 1	
I$_{LU}$	Latchup Current (Note 2)		±100	mA
ESD	ESD Protection (Note 3)	Human Body Model	4000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Moisture Sensitivity Level (MSL): 1 per IPC/JEDEC standard: J−STD−020A.
2. Latch up Current Maximum Rating: ±100 mA per JEDEC standard: JESD78.
3. This device series contains ESD protection and passes the following tests:
   Human Body Model (HBM) ±4.0 kV per JEDEC standard: JESD22−A114 for all pins.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V$_{CCEN}$	Positive DC Supply Voltage		2.7	5.5	V
V$_{IS}$	Switch Input / Output Voltage (Note 4)	HDP, HDN	0	3.7	V
		AUDP, AUDN	−2.0	2.0	
		D+, D−	−2.0	3.7	
V$_{IN}$	Digital Control Input Voltage		GND	V$_{CC}$	V
T$_A$	Operating Temperature Range		−40	+85	°C

4. f the audio channel is not in use, it is recommended that no signals are applied on the audio inputs AUDN and AUDP.

DC ELECTRICAL CHARACTERISTICS (Typical values are at V_{CC} = +3.6 V and T_A = +25 ºC)

Symbol	Parameter	Test Conditions	V_{CC} (V)	−40 ºC to 85 ºC			Unit
				Min	Typ	Max	
POWER SUPPLY							
I_{CC}	Supply Current	I_{IS} = 0 mA	4.2	–	23	105	μA
Control Logic (EN, SEL)							
V_{IH}	Input High Voltage		4.2	1.5	–	–	V
			3.6	1.4	–	–	
			2.7	1.3	–	–	
V_{IL}	Input Low Voltage		4.2	–	–	0.4	V
			3.6	–	–	0.4	
			2.7	–	–	0.4	
V_{IHYS}	Input Hysteresis		2.7 − 5.5	–	250	–	mV
I_{IN}	Leakage Current		2.7 − 5.5	–	–	±150	nA
AUDIO SWITCH (AUDP/AUDN ↔ D+/D−)							
R_{ON}	ON−Resistance	V_{IS} = −2.0 V to 2.0 V, I_{IS} = 50 mA	3.0	–	3	5	Ω
ΔR_{ON}	ON−Resistance Matching Between Channels	V_{IS} = −2.0 V to 2.0 V, I_{IS} = 50 mA	3.0	–	0.05	–	Ω
$R_{FLAT(ON)}$	ON Resistance Flatness	V_{IS} = −2.0 V to 2.0 V, I_{IS} = 50 mA	3.0	–	0.002	–	Ω
R_{SH}	Shunt Resistance		3.6	–	125	200	Ω
DATA SWITCH (HDP/HDN ↔ D+/D−)							
R_{ON}	ON−Resistance	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	–	5	7.5	Ω
ΔR_{ON}	ON−Resistance Matching Between Channels	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	–	0.02	–	Ω
$R_{FLAT(ON)}$	ON Resistance Flatness	V_{IS} = 0 V to 1.7 V, I_{IS} = 15 mA	3.0	–	0.003	–	Ω
$I_{SW(OFF)}$	OFF−State Leakage	V_{IS} = 0 V to 3.6	3.6	–	–	200	nA
$I_{SW(ON)}$	ON−State Leakage	V_{IS} = 0 V to 3.6	3.6	–	–	±200	nA

AC ELECTRICAL CHARACTERISTICS (Typical values are at V_{CC} = +3.6 V and T_A = +25 ºC)

Symbol	Parameter	Test Conditions	V_{CC} (V)	–40 ºC to 85 ºC			Unit
				Min	Typ	Max	
AUDIO SWITCH (AUDP/AUDN ↔ D+/D−)							
THD	Audio THD	f = 20 Hz to 20 kHz, V_{IS} = 0.4 V_{RMS}, DC Bias = 0 V, R_L = 16 Ω	2.7 − 5.5	–	0.002	–	%
PSRR	Power Supply Ripple Rejection	From V_{CC} unto AUDP/AUDN, f = 217 Hz, R_L = 16 Ω	2.7 − 5.5	–	118	–	dB
DATA SWITCH (HDP/HDN ↔ D+/D−)							
C_{ON}	Equivalent ON−Capacitance	Switch ON, f = 1 MHz	3.6	–	4.84	–	pF
C_{OFF}	Equivalent OFF−Capacitance	Switch OFF, f = 1 MHz	3.6	–	2.06	–	pF
D_{IL}	Differential Insertion Loss	f = 10 MHz	2.7 − 5.5	–	−0.42	–	dB
		f = 800 MHz	2.7 − 5.5	–	−1.89	–	
		f = 1.1 GHz	2.7 − 5.5	–	−3.01	–	
D_{ISO}	Differential Off−Isolation	f = 10 MHz	2.7 − 5.5	–	−60	–	dB
		f = 800 MHz	2.7 − 5.5	–	−15	–	
		f = 1.1 GHz	2.7 − 5.5	–	−15	–	
D_{CTK}	Differential Crosstalk	f = 10 MHz	2.7 − 5.5	–	−67	–	dB
		f = 800 MHz	2.7 − 5.5	–	−23	–	
		f = 1.1 GHz	2.7 − 5.5	–	−19	–	
PSRR	Power Supply Ripple Rejection	From V_{CC} unto D+/D−, f = 217 Hz, R_L = 50 Ω	2.7 − 5.5	–	108	–	dB
DYNAMIC TIMING							
t_{PD}	Propagation Delay (Notes 5 and 6)	V_{NOn} or V_{NCn} = 0V, R_L = 50 Ω,	2.7 − 5.5	–	0.25	–	ns
t_{ON}	Turn−On Time	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 − 5.5				μs
		EN or SEL to AUDP/AUDN		–	2.2	–	
		EN or SEL to HDP/HDN		–	6.2	–	
t_{OFF}	Turn−Off Time	V_{IS} = 1 V, R_L = 50 Ω, C_L = 7 pF (fixture only)	2.7 − 5.5				ns
		EN or SEL to AUDP/AUDN		–	67	–	
		EN or SEL to HDP/HDN		–	1200	–	
$t_{sk(b−b)}$	Bit to bit skew	Within the same differential channel	2.7 − 5.5	–	5	–	ps
$t_{sk(ch−ch)}$	Channel to channel skew	Maximum skew between all channels	2.7 − 5.5	–	5	–	ps

5. Guaranteed by design.
6. No other delays than the RC network formed by the load resistance and the load capacitance of the switch are added on the bus. For a 10 pF load, this delay is 5 ns which is much smaller than rise and fall time of typical driving systems. Propagation delays on the bus are determined by the driving circuit on the driving side and its interactions with the load of the driven side.

PARAMETER MEASUREMENT INFORMATION
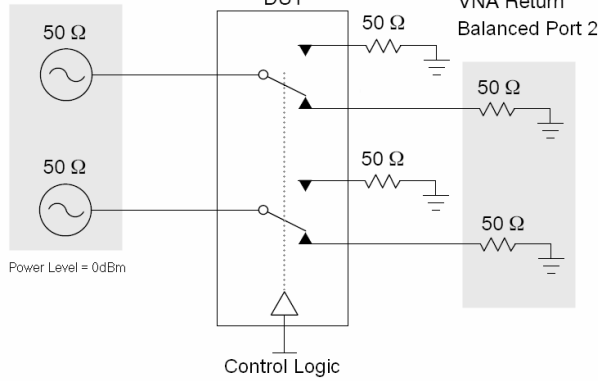
Figure 3. Differential Insertion Loss (S_{DD21})
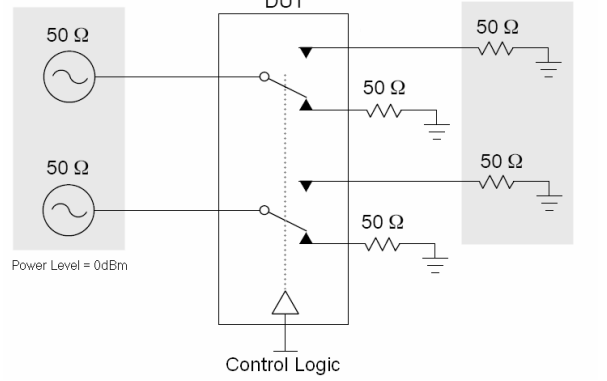
Figure 4. Differential Off Isolation (S_{DD21})
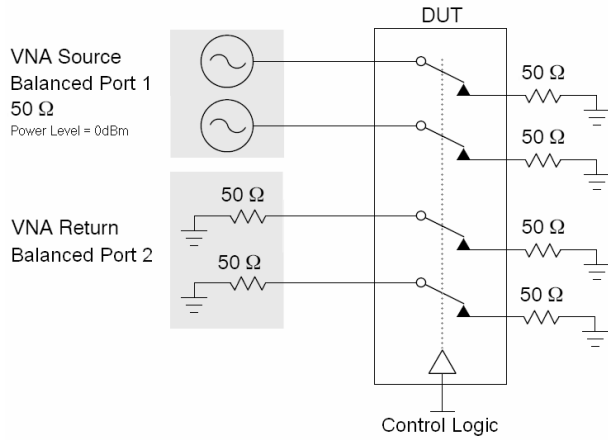
Figure 5. Differential Crosstalk (S_{DD21})

$$t_{skew} = |t_{PLH1}-t_{PLH2}| \text{ or } |t_{PHL1}-t_{PHL2}|$$
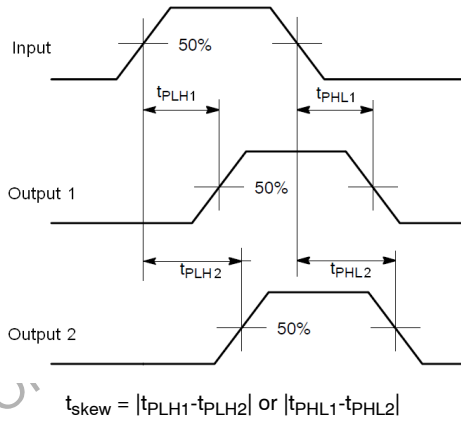
Figure 6. Bit−to−Bit and Channel−to−Channel Skew
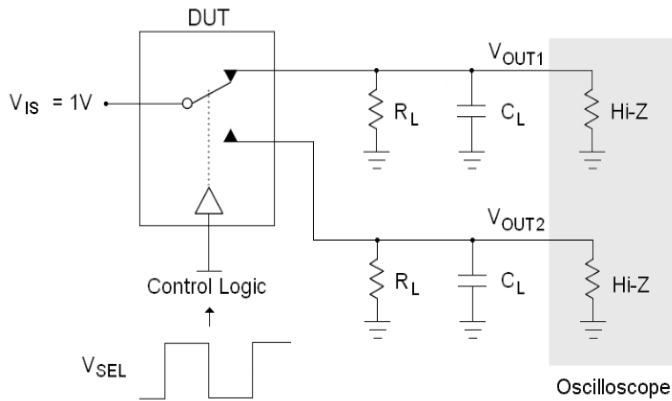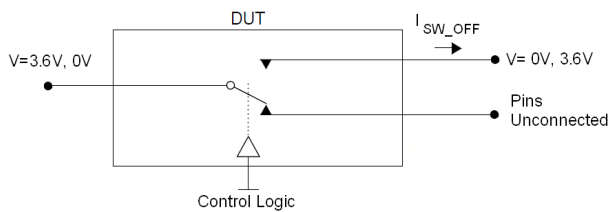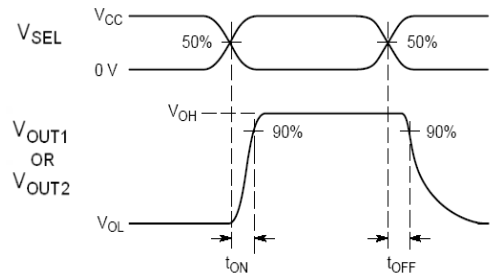

Figure 7. t_{ON} and t_{OFF}
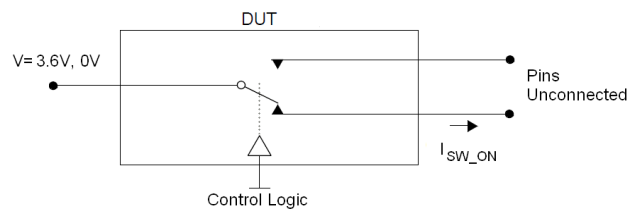

Figure 8. Off State Leakage

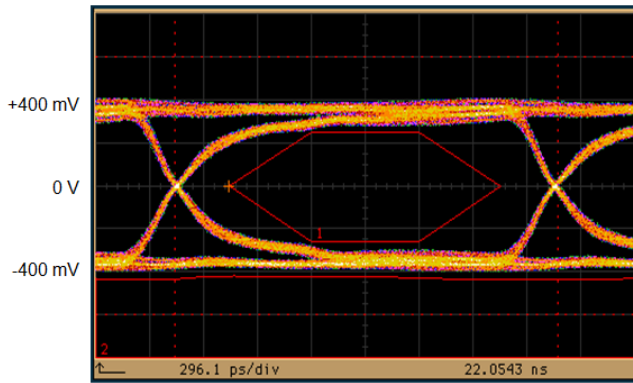Figure 9. On State Leakage

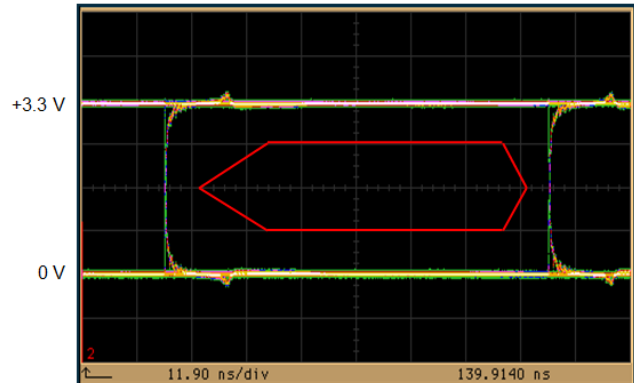## TYPICAL OPERATING CHARACTERISTICS

Figure 10. USB 2.0 High Speed Eye Diagram

Figure 11. USB 1.1 Full Speed Eye Diagram
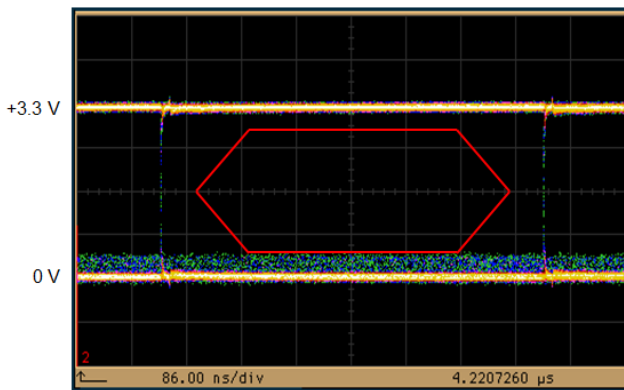
Figure 12. USB 1.0 Low Speed Eye Diagram
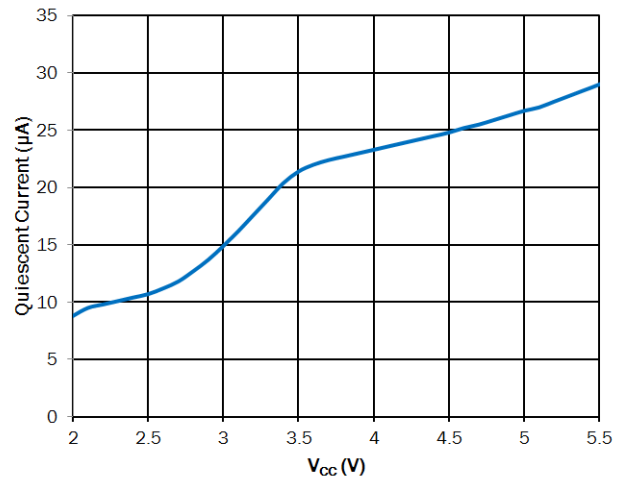
Figure 13. Product Supply Current
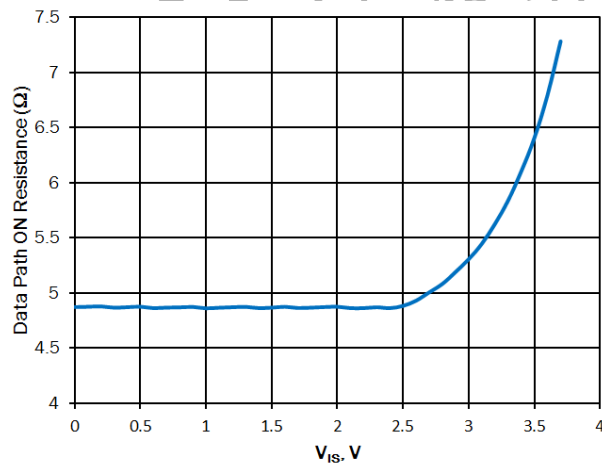
Figure 14. Data Path On Resistance
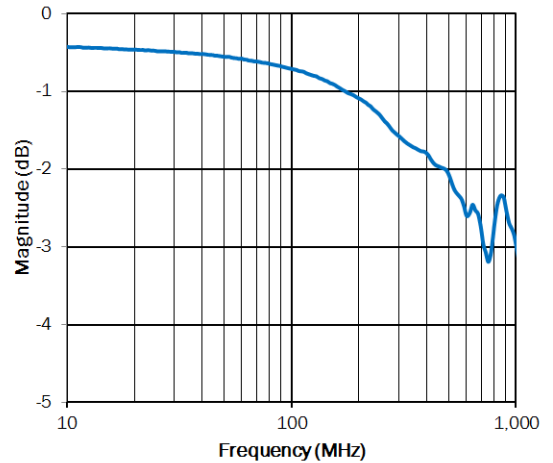
**Figure 15. Data Switch
Differential Insertion Loss**
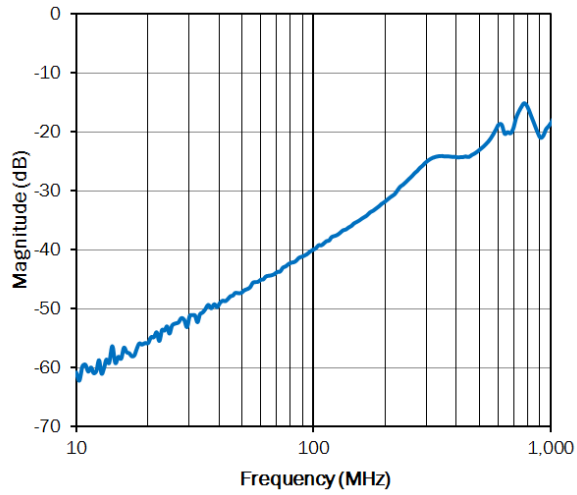
**Figure 16. Data Switch
Differential Off−Isolation**
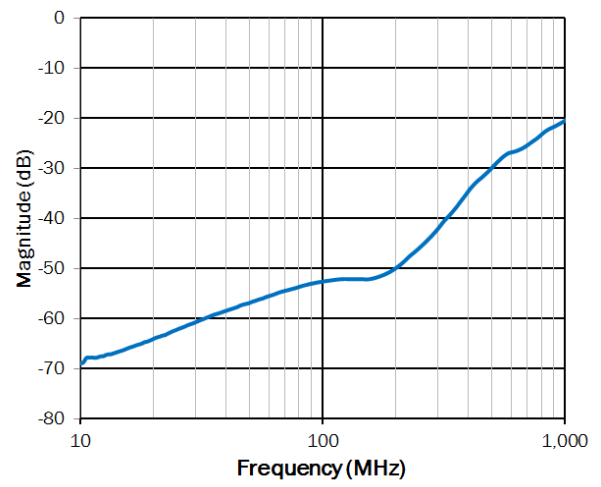
**Figure 17. Data Switch Differential
Crosstalk**
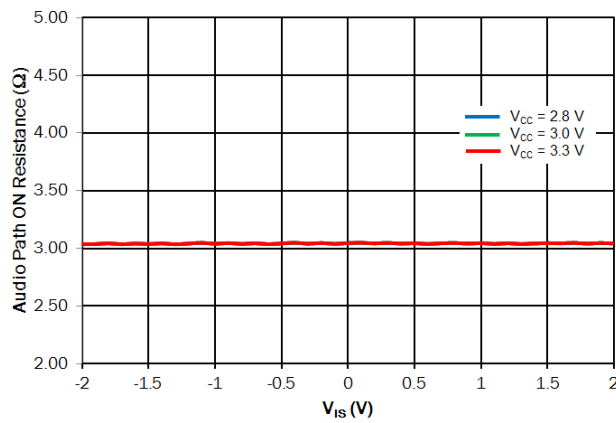
Figure 18. Audio Path On Resistance
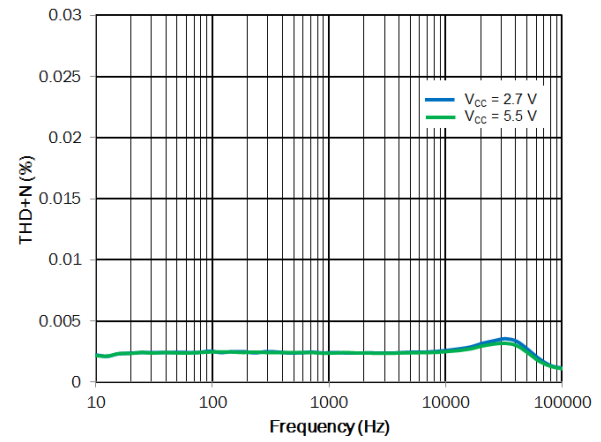
Figure 19. Audio THD

onsemi
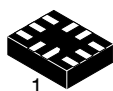
UQFN10 1.4x1.8, 0.4P
CASE 488AT
ISSUE A

DATE 01 AUG 2007

SCALE 5:1

1

D

A

PIN 1 REFERENCE

2X | △ | 0.10 | C

2X | △ | 0.10 | C

E

B

TOP VIEW

EDGE OF PACKAGE

L1

DETAIL A
Bottom View
(Optional)

// | 0.05 | C

10X | △ | 0.05 | C

A

A1

C | SEATING PLANE

SIDE VIEW

EXPOSED Cu

MOLD CMPD

A1

A3

DETAIL B
Side View
(Optional)
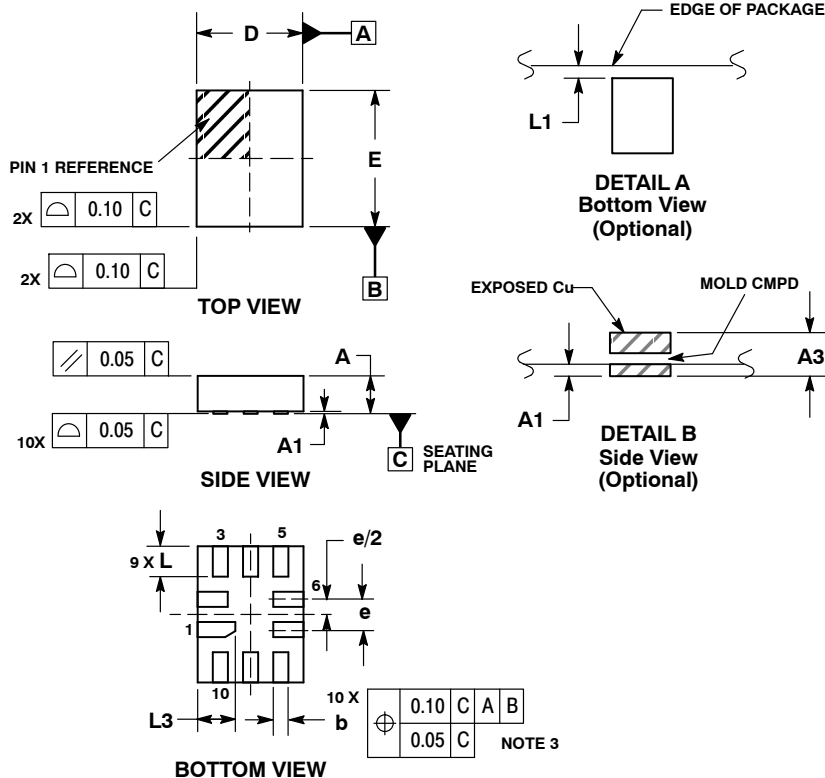
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| DIM | MILLIMETERS | |
	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
D	1.40 BSC	
E	1.80 BSC	
e	0.40 BSC	
L	0.30	0.50
L1	0.00	0.15
L3	0.40	0.60

GENERIC
MARKING DIAGRAM*

XXM■
○   ■
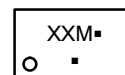
XX = Specific Device Code
M = Date Code
■ = Pb–Free Package
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ■", may or may not be present.

3   5   e/2

9 X L

6

1

e

10

L3   b   10 X

10 X | ⊕ | 0.10 | C | A | B
| | 0.05 | C | | NOTE 3

BOTTOM VIEW

MOUNTING FOOTPRINT

1.700 / 0.0669

9 X 0.563 / 0.0221

0.663 / 0.0261

0.200 / 0.0079

1

2.100 / 0.0827

0.400 / 0.0157 PITCH

10 X 0.225 / 0.0089

SCALE 20:1 (mm / inches)
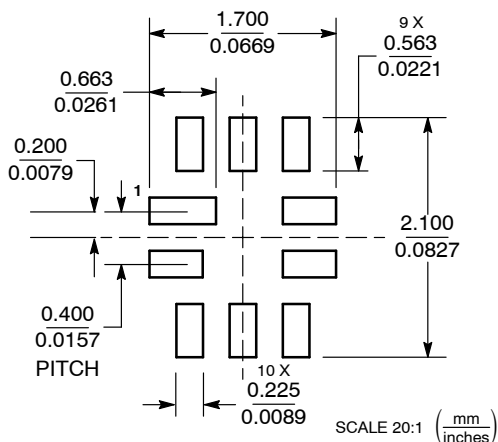
DOCUMENT NUMBER:	98AON22493D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	10 PIN UQFN, 1.4 X 1.8, 0.4P	**PAGE 1 OF 1**

ADDITIONAL INFORMATION

◊